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Understanding [Embedded - CPLDs \(Complex Programmable Logic Devices\)](#)

Embedded - CPLDs, or Complex Programmable Logic Devices, are highly versatile digital logic devices used in electronic systems. These programmable components are designed to perform complex logical operations and can be customized for specific applications. Unlike fixed-function ICs, CPLDs offer the flexibility to reprogram their configuration, making them an ideal choice for various embedded systems. They consist of a set of logic gates and programmable interconnects, allowing designers to implement complex logic circuits without needing custom hardware.

Applications of Embedded - CPLDs

Details

Product Status	Active
Programmable Type	In System Programmable
Delay Time tpd(1) Max	5.4 ns
Voltage Supply - Internal	1.71V ~ 1.89V
Number of Logic Elements/Blocks	570
Number of Macrocells	440
Number of Gates	-
Number of I/O	160
Operating Temperature	-40°C ~ 100°C (TJ)
Mounting Type	Surface Mount
Package / Case	256-BGA
Supplier Device Package	256-FBGA (17x17)
Purchase URL	https://www.e-xfl.com/product-detail/intel/epm570gf256i5

Introduction

The MAX[®] II family of instant-on, non-volatile CPLDs is based on a 0.18- μ m, 6-layer-metal-flash process, with densities from 240 to 2,210 logic elements (LEs) (128 to 2,210 equivalent macrocells) and non-volatile storage of 8 Kbits. MAX II devices offer high I/O counts, fast performance, and reliable fitting versus other CPLD architectures. Featuring MultiVolt core, a user flash memory (UFM) block, and enhanced in-system programmability (ISP), MAX II devices are designed to reduce cost and power while providing programmable solutions for applications such as bus bridging, I/O expansion, power-on reset (POR) and sequencing control, and device configuration control.

Features

The MAX II CPLD has the following features:

- Low-cost, low-power CPLD
- Instant-on, non-volatile architecture
- Standby current as low as 25 μ A
- Provides fast propagation delay and clock-to-output times
- Provides four global clocks with two clocks available per logic array block (LAB)
- UFM block up to 8 Kbits for non-volatile storage
- MultiVolt core enabling external supply voltages to the device of either 3.3 V/2.5 V or 1.8 V
- MultiVolt I/O interface supporting 3.3-V, 2.5-V, 1.8-V, and 1.5-V logic levels
- Bus-friendly architecture including programmable slew rate, drive strength, bus-hold, and programmable pull-up resistors
- Schmitt triggers enabling noise tolerant inputs (programmable per pin)
- I/Os are fully compliant with the Peripheral Component Interconnect Special Interest Group (PCI SIG) PCI Local Bus Specification, Revision 2.2 for 3.3-V operation at 66 MHz
- Supports hot-socketing
- Built-in Joint Test Action Group (JTAG) boundary-scan test (BST) circuitry compliant with IEEE Std. 1149.1-1990
- ISP circuitry compliant with IEEE Std. 1532

MAX II devices are available in space-saving FineLine BGA, Micro FineLine BGA, and thin quad flat pack (TQFP) packages (refer to [Table 1-3](#) and [Table 1-4](#)). MAX II devices support vertical migration within the same package (for example, you can migrate between the EPM570, EPM1270, and EPM2210 devices in the 256-pin FineLine BGA package). Vertical migration means that you can migrate to devices whose dedicated pins and JTAG pins are the same and power pins are subsets or supersets for a given package across device densities. The largest density in any package has the highest number of power pins; you must lay out for the largest planned density in a package to provide the necessary power pins for migration. For I/O pin migration across densities, cross reference the available I/O pins using the device pin-outs for all planned densities of a given package type to identify which I/O pins can be migrated. The Quartus® II software can automatically cross-reference and place all pins for you when given a device migration list.

Table 1-3. MAX II Packages and User I/O Pins

Device	68-Pin Micro FineLine BGA (1)	100-Pin Micro FineLine BGA (1)	100-Pin FineLine BGA	100-Pin TQFP	144-Pin TQFP	144-Pin Micro FineLine BGA (1)	256-Pin Micro FineLine BGA (1)	256-Pin FineLine BGA	324-Pin FineLine BGA
EPM240 EPM240G	—	80	80	80	—	—	—	—	—
EPM570 EPM570G	—	76	76	76	116	—	160	160	—
EPM1270 EPM1270G	—	—	—	—	116	—	212	212	—
EPM2210 EPM2210G	—	—	—	—	—	—	—	204	272
EPM240Z	54	80	—	—	—	—	—	—	—
EPM570Z	—	76	—	—	—	116	160	—	—

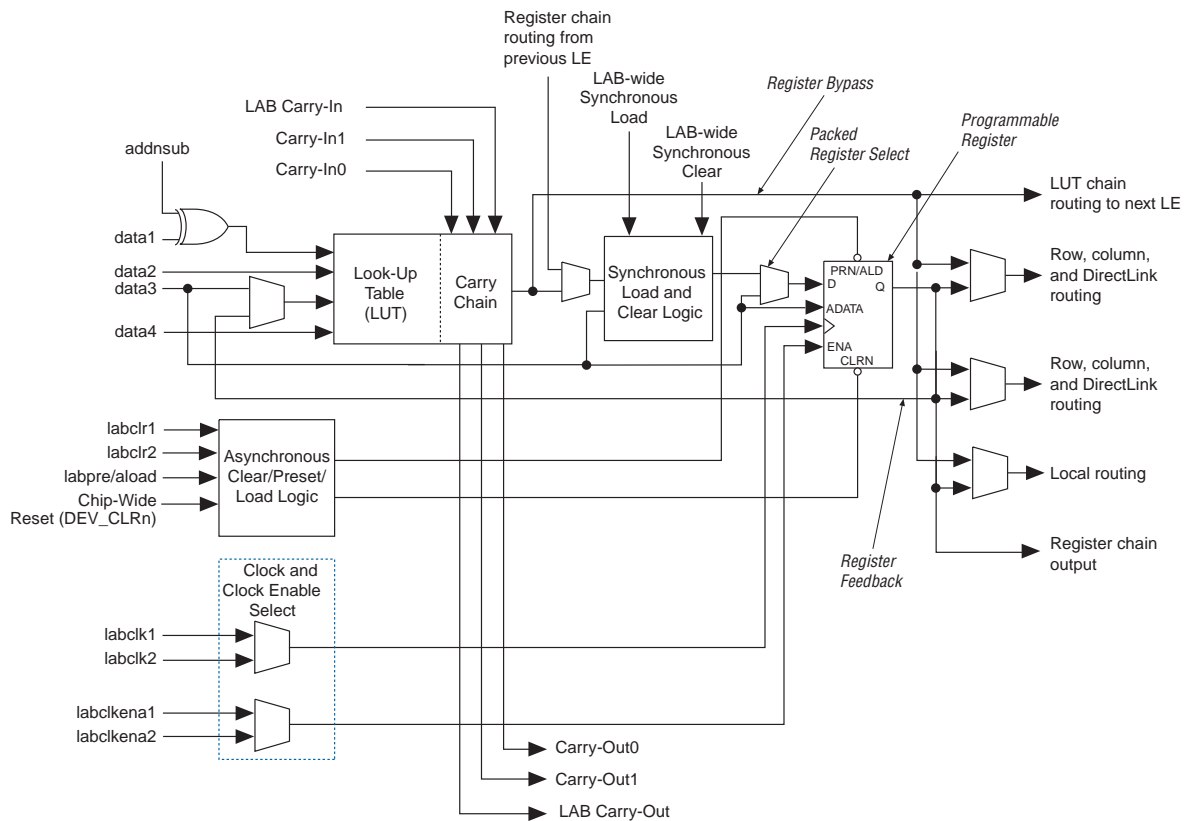
Note to Table 1-3:

(1) Packages available in lead-free versions only.

Table 1-4. MAX II TQFP, FineLine BGA, and Micro FineLine BGA Package Sizes

Package	68-Pin Micro FineLine BGA	100-Pin Micro FineLine BGA	100-Pin FineLine BGA	100-Pin TQFP	144-Pin TQFP	144-Pin Micro FineLine BGA	256-Pin Micro FineLine BGA	256-Pin FineLine BGA	324-Pin FineLine BGA
Pitch (mm)	0.5	0.5	1	0.5	0.5	0.5	0.5	1	1
Area (mm ²)	25	36	121	256	484	49	121	289	361
Length × width (mm × mm)	5 × 5	6 × 6	11 × 11	16 × 16	22 × 22	7 × 7	11 × 11	17 × 17	19 × 19

Figure 2-6. MAX II LE



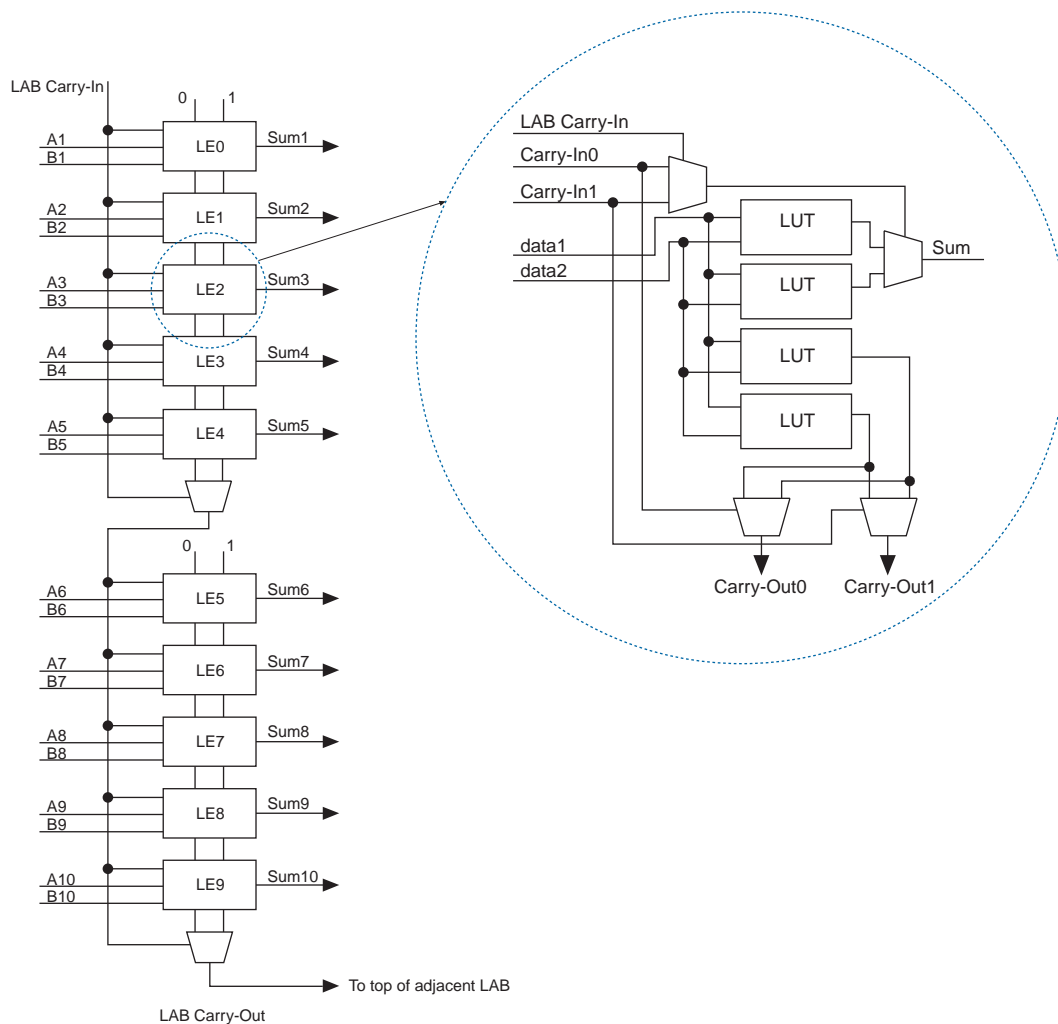
Each LE's programmable register can be configured for D, T, JK, or SR operation. Each register has data, true asynchronous load data, clock, clock enable, clear, and asynchronous load/preset inputs. Global signals, general-purpose I/O pins, or any LE can drive the register's clock and clear control signals. Either general-purpose I/O pins or LEs can drive the clock enable, preset, asynchronous load, and asynchronous data. The asynchronous load data input comes from the data3 input of the LE. For combinational functions, the LUT output bypasses the register and drives directly to the LE outputs.

Each LE has three outputs that drive the local, row, and column routing resources. The LUT or register output can drive these three outputs independently. Two LE outputs drive column or row and DirectLink routing connections and one drives local interconnect resources. This allows the LUT to drive one output while the register drives another output. This register packing feature improves device utilization because the device can use the register and the LUT for unrelated functions. Another special packing mode allows the register output to feed back into the LUT of the same LE so that the register is packed with its own fan-out LUT. This provides another mechanism for improved fitting. The LE can also drive out registered and unregistered versions of the LUT output.

The speed advantage of the carry-select chain is in the parallel precomputation of carry chains. Since the LAB carry-in selects the precomputed carry chain, not every LE is in the critical path. Only the propagation delays between LAB carry-in generation (LE 5 and LE 10) are now part of the critical path. This feature allows the MAX II architecture to implement high-speed counters, adders, multipliers, parity functions, and comparators of arbitrary width.

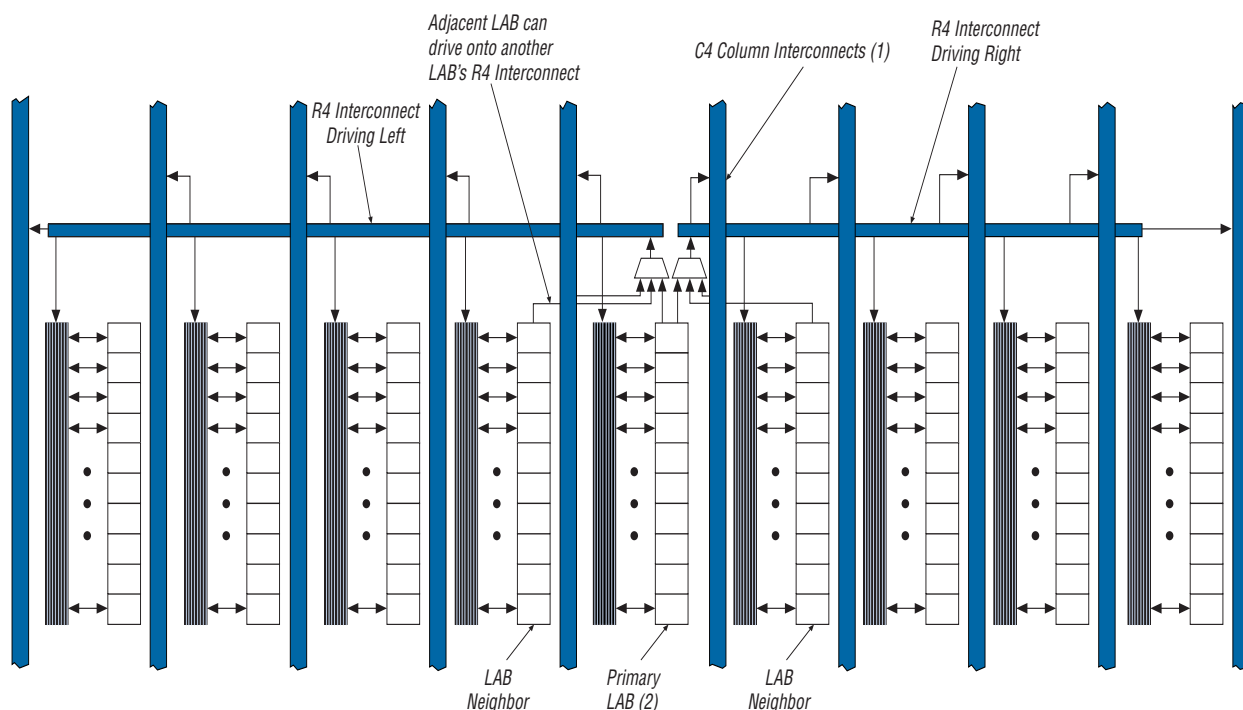
Figure 2-9 shows the carry-select circuitry in an LAB for a 10-bit full adder. One portion of the LUT generates the sum of two bits using the input signals and the appropriate carry-in bit; the sum is routed to the output of the LE. The register can be bypassed for simple adders or used for accumulator functions. Another portion of the LUT generates carry-out bits. An LAB-wide carry-in bit selects which chain is used for the addition of given inputs. The carry-in signal for each chain, carry-in0 or carry-in1, selects the carry-out to carry forward to the carry-in signal of the next-higher-order bit. The final carry-out signal is routed to an LE, where it is fed to local, row, or column interconnects.

Figure 2-9. Carry-Select Chain



The R4 interconnects span four LABs and are used for fast row connections in a four-LAB region. Every LAB has its own set of R4 interconnects to drive either left or right. Figure 2-10 shows R4 interconnect connections from an LAB. R4 interconnects can drive and be driven by row IOEs. For LAB interfacing, a primary LAB or horizontal LAB neighbor can drive a given R4 interconnect. For R4 interconnects that drive to the right, the primary LAB and right neighbor can drive on to the interconnect. For R4 interconnects that drive to the left, the primary LAB and its left neighbor can drive on to the interconnect. R4 interconnects can drive other R4 interconnects to extend the range of LABs they can drive. R4 interconnects can also drive C4 interconnects for connections from one row to another.

Figure 2-10. R4 Interconnect Connections



Notes to Figure 2-10:

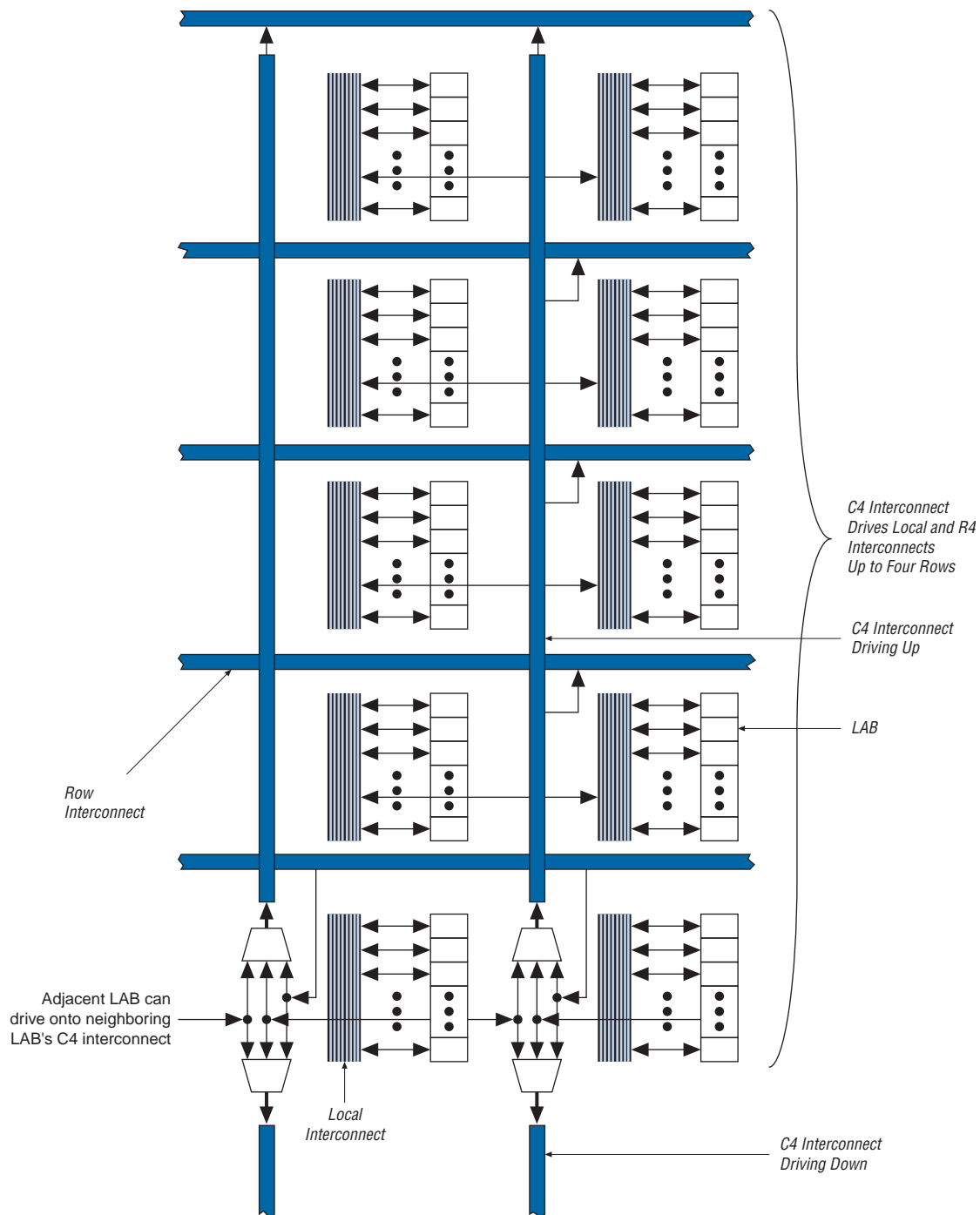
- (1) C4 interconnects can drive R4 interconnects.
- (2) This pattern is repeated for every LAB in the LAB row.

The column interconnect operates similarly to the row interconnect. Each column of LABs is served by a dedicated column interconnect, which vertically routes signals to and from LABs and row and column IOEs. These column resources include:

- LUT chain interconnects within an LAB
- Register chain interconnects within an LAB
- C4 interconnects traversing a distance of four LABs in an up and down direction

MAX II devices include an enhanced interconnect structure within LABs for routing LE output to LE input connections faster using LUT chain connections and register chain connections. The LUT chain connection allows the combinational output of an LE to directly drive the fast input of the LE right below it, bypassing the local interconnect. These resources can be used as a high-speed connection for wide fan-in

Figure 2-12. C4 Interconnect Connections *(Note 1)*



Note to Figure 2-12:

- (1) Each C4 interconnect can drive either up or down four rows.

The UFM block communicates with the logic array similar to LAB-to-LAB interfaces. The UFM block connects to row and column interconnects and has local interconnect regions driven by row and column interconnects. This block also has DirectLink interconnects for fast connections to and from a neighboring LAB. For more information about the UFM interface to the logic array, see “User Flash Memory Block” on page 2-18.

Table 2-2 shows the MAX II device routing scheme.

Table 2-2. MAX II Device Routing Scheme

Source	Destination										
	LUT Chain	Register Chain	Local (1)	DirectLink (1)	R4 (1)	C4 (1)	LE	UFM Block	Column IOE	Row IOE	Fast I/O (1)
LUT Chain	—	—	—	—	—	—	✓	—	—	—	—
Register Chain	—	—	—	—	—	—	✓	—	—	—	—
Local Interconnect	—	—	—	—	—	—	✓	✓	✓	✓	—
DirectLink Interconnect	—	—	✓	—	—	—	—	—	—	—	—
R4 Interconnect	—	—	✓	—	✓	✓	—	—	—	—	—
C4 Interconnect	—	—	✓	—	✓	✓	—	—	—	—	—
LE	✓	✓	✓	✓	✓	✓	—	—	✓	✓	✓
UFM Block	—	—	✓	✓	✓	✓	—	—	—	—	—
Column IOE	—	—	—	—	—	✓	—	—	—	—	—
Row IOE	—	—	—	✓	✓	✓	—	—	—	—	—

Note to Table 2-2:

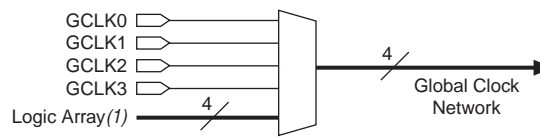
(1) These categories are interconnects.

Global Signals

Each MAX II device has four dual-purpose dedicated clock pins (GCLK[3..0], two pins on the left side and two pins on the right side) that drive the global clock network for clocking, as shown in Figure 2-13. These four pins can also be used as general-purpose I/O if they are not used to drive the global clock network.

The four global clock lines in the global clock network drive throughout the entire device. The global clock network can provide clocks for all resources within the device including LEs, LAB local interconnect, IOEs, and the UFM block. The global clock lines can also be used for global control signals, such as clock enables, synchronous or asynchronous clears, presets, output enables, or protocol control signals such as TRDY and IRDY for PCI. Internal logic can drive the global clock network for internally-generated global clocks and control signals. Figure 2-13 shows the various sources that drive the global clock network.

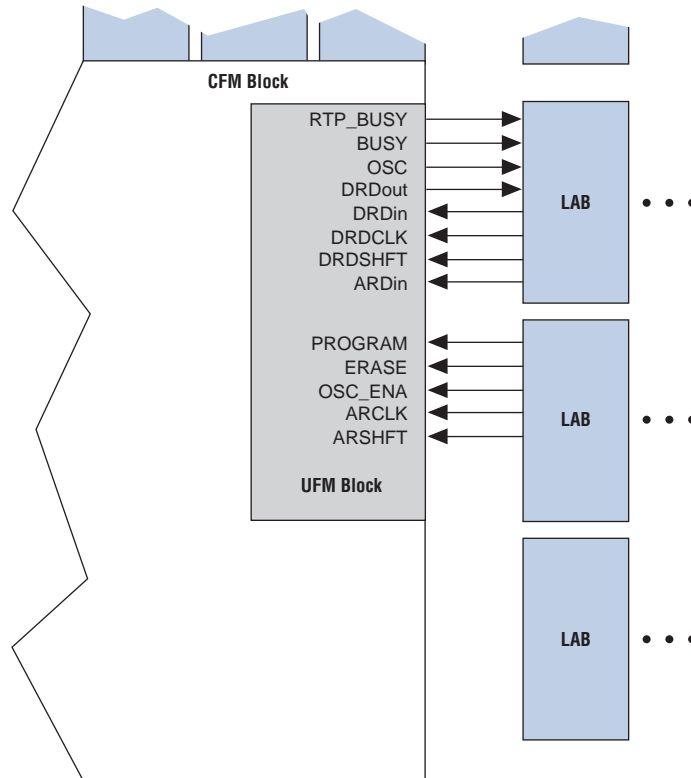
Figure 2-13. Global Clock Generation



Note to Figure 2-13:

(1) Any I/O pin can use a MultiTrack interconnect to route as a logic array-generated global clock signal.

The global clock network drives to individual LAB column signals, LAB column clocks [3..0], that span an entire LAB column from the top to the bottom of the device. Unused global clocks or control signals in a LAB column are turned off at the LAB column clock buffers shown in Figure 2-14. The LAB column clocks [3..0] are multiplexed down to two LAB clock signals and one LAB clear signal. Other control signal types route from the global clock network into the LAB local interconnect. See “LAB Control Signals” on page 2-5 for more information.

Figure 2-17. EPM570, EPM1270, and EPM2210 UFM Block LAB Row Interface

MultiVolt Core

The MAX II architecture supports the MultiVolt core feature, which allows MAX II devices to support multiple V_{CC} levels on the V_{CCINT} supply. An internal linear voltage regulator provides the necessary 1.8-V internal voltage supply to the device. The voltage regulator supports 3.3-V or 2.5-V supplies on its inputs to supply the 1.8-V internal voltage to the device, as shown in Figure 2-18. The voltage regulator is not guaranteed for voltages that are between the maximum recommended 2.5-V operating voltage and the minimum recommended 3.3-V operating voltage.

The MAX IIG and MAX IIZ devices use external 1.8-V supply. The 1.8-V V_{CC} external supply powers the device core directly.

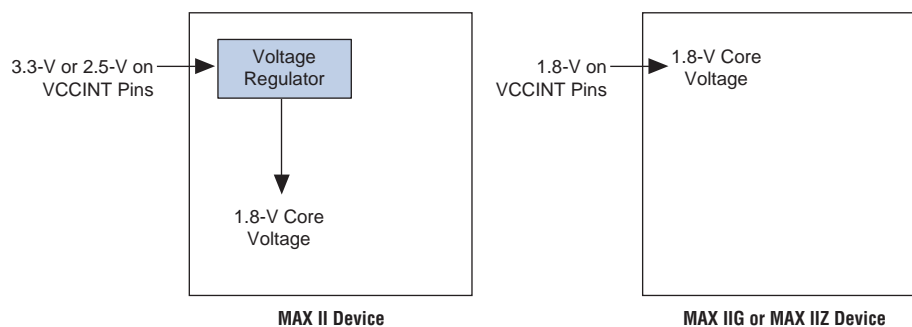
Figure 2-18. MultiVolt Core Feature in MAX II Devices

Table 2-6. Programmable Drive Strength *(Note 1)*

I/O Standard	IOH/IOL Current Strength Setting (mA)
3.3-V LVTTTL	16
	8
3.3-V LVCMOS	8
	4
2.5-V LVTTTL/LVCMOS	14
	7
1.8-V LVTTTL/LVCMOS	6
	3
1.5-V LVCMOS	4
	2

Note to Table 2-6:

- (1) The I_{OH} current strength numbers shown are for a condition of a $V_{OUT} = V_{OH}$ minimum, where the V_{OH} minimum is specified by the I/O standard. The I_{OL} current strength numbers shown are for a condition of a $V_{OUT} = V_{OL}$ maximum, where the V_{OL} maximum is specified by the I/O standard. For 2.5-V LVTTTL/LVCMOS, the I_{OH} condition is $V_{OUT} = 1.7$ V and the I_{OL} condition is $V_{OUT} = 0.7$ V.

Slew-Rate Control

The output buffer for each MAX II device I/O pin has a programmable output slew-rate control that can be configured for low noise or high-speed performance. A faster slew rate provides high-speed transitions for high-performance systems. However, these fast transitions may introduce noise transients into the system. A slow slew rate reduces system noise, but adds a nominal output delay to rising and falling edges. The lower the voltage standard (for example, 1.8-V LVTTTL) the larger the output delay when slow slew is enabled. Each I/O pin has an individual slew-rate control, allowing the designer to specify the slew rate on a pin-by-pin basis. The slew-rate control affects both the rising and falling edges.

Open-Drain Output

MAX II devices provide an optional open-drain (equivalent to open-collector) output for each I/O pin. This open-drain output enables the device to provide system-level control signals (for example, interrupt and write enable signals) that can be asserted by any of several devices. This output can also provide an additional wired-OR plane.

Programmable Ground Pins

Each unused I/O pin on MAX II devices can be used as an additional ground pin. This programmable ground feature does not require the use of the associated LEs in the device. In the Quartus II software, unused pins can be set as programmable GND on a global default basis or they can be individually assigned. Unused pins also have the option of being set as tri-stated input pins.

Bus Hold

Each MAX II device I/O pin provides an optional bus-hold feature. The bus-hold circuitry can hold the signal on an I/O pin at its last-driven state. Since the bus-hold feature holds the last-driven state of the pin until the next input signal is present, an external pull-up or pull-down resistor is not necessary to hold a signal level when the bus is tri-stated.

The bus-hold circuitry also pulls undriven pins away from the input threshold voltage where noise can cause unintended high-frequency switching. The designer can select this feature individually for each I/O pin. The bus-hold output will drive no higher than V_{CCIO} to prevent overdriving signals. If the bus-hold feature is enabled, the device cannot use the programmable pull-up option.

The bus-hold circuitry uses a resistor to pull the signal level to the last driven state. The *DC and Switching Characteristics* chapter in the *MAX II Device Handbook* gives the specific sustaining current for each V_{CCIO} voltage level driven through this resistor and overdrive current used to identify the next-driven input level.

The bus-hold circuitry is only active after the device has fully initialized. The bus-hold circuit captures the value on the pin present at the moment user mode is entered.

Programmable Pull-Up Resistor

Each MAX II device I/O pin provides an optional programmable pull-up resistor during user mode. If the designer enables this feature for an I/O pin, the pull-up resistor holds the output to the V_{CCIO} level of the output pin's bank.



The programmable pull-up resistor feature should not be used at the same time as the bus-hold feature on a given I/O pin.

Programmable Input Delay

The MAX II IOE includes a programmable input delay that is activated to ensure zero hold times. A path where a pin directly drives a register, with minimal routing between the two, may require the delay to ensure zero hold time. However, a path where a pin drives a register through long routing or through combinational logic may not require the delay to achieve a zero hold time. The Quartus II software uses this delay to ensure zero hold times when needed.

MultiVolt I/O Interface

The MAX II architecture supports the MultiVolt I/O interface feature, which allows MAX II devices in all packages to interface with systems of different supply voltages. The devices have one set of VCC pins for internal operation (V_{CCINT}), and up to four sets for input buffers and I/O output driver buffers (V_{CCIO}), depending on the number of I/O banks available in the devices where each set of VCC pins powers one I/O bank. The EPM240 and EPM570 devices have two I/O banks respectively while the EPM1270 and EPM2210 devices have four I/O banks respectively.

Connect VCCIO pins to either a 1.5-V, 1.8 V, 2.5-V, or 3.3-V power supply, depending on the output requirements. The output levels are compatible with systems of the same voltage as the power supply (that is, when VCCIO pins are connected to a 1.5-V power supply, the output levels are compatible with 1.5-V systems). When VCCIO pins are connected to a 3.3-V power supply, the output high is 3.3 V and is compatible with 3.3-V or 5.0-V systems. Table 2-7 summarizes MAX II MultiVolt I/O support.

Table 2-7. MAX II MultiVolt I/O Support (Note 1)

VCCIO (V)	Input Signal					Output Signal				
	1.5 V	1.8 V	2.5 V	3.3 V	5.0 V	1.5 V	1.8 V	2.5 V	3.3 V	5.0 V
1.5	✓	✓	✓	✓	—	✓	—	—	—	—
1.8	✓	✓	✓	✓	—	✓ (2)	✓	—	—	—
2.5	—	—	✓	✓	—	✓ (3)	✓ (3)	✓	—	—
3.3	—	—	✓ (4)	✓	✓ (5)	✓ (6)	✓ (6)	✓ (6)	✓	✓ (7)

Notes to Table 2-7:

- (1) To drive inputs higher than V_{CCIO} but less than 4.0 V including the overshoot, disable the I/O clamp diode. However, to drive 5.0-V inputs to the device, enable the I/O clamp diode to prevent V_I from rising above 4.0 V.
- (2) When V_{CCIO} = 1.8 V, a MAX II device can drive a 1.5-V device with 1.8-V tolerant inputs.
- (3) When V_{CCIO} = 2.5 V, a MAX II device can drive a 1.5-V or 1.8-V device with 2.5-V tolerant inputs.
- (4) When V_{CCIO} = 3.3 V and a 2.5-V input signal feeds an input pin, the VCCIO supply current will be slightly larger than expected.
- (5) MAX II devices can be 5.0-V tolerant with the use of an external resistor and the internal I/O clamp diode on the EPM1270 and EPM2210 devices.
- (6) When V_{CCIO} = 3.3 V, a MAX II device can drive a 1.5-V, 1.8-V, or 2.5-V device with 3.3-V tolerant inputs.
- (7) When V_{CCIO} = 3.3 V, a MAX II device can drive a device with 5.0-V TTL inputs but not 5.0-V CMOS inputs. In the case of 5.0-V CMOS, open-drain setting with internal I/O clamp diode (available only on EPM1270 and EPM2210 devices) and external resistor is required.



For information about output pin source and sink current guidelines, refer to the [AN 428: MAX II CPLD Design Guidelines](#).

Referenced Documents

This chapter referenced the following documents:

- [AN 428: MAX II CPLD Design Guidelines](#)
- [DC and Switching Characteristics](#) chapter in the *MAX II Device Handbook*
- [Hot Socketing and Power-On Reset in MAX II Devices](#) chapter in the *MAX II Device Handbook*
- [Using User Flash Memory in MAX II Devices](#) chapter in the *MAX II Device Handbook*

Table 3–1. MAX II JTAG Instructions (Part 2 of 2)

JTAG Instruction	Instruction Code	Description
CLAMP (1)	00 0000 1010	Places the 1-bit bypass register between the TDI and TDO pins, which allows the boundary scan test data to pass synchronously through selected devices to adjacent devices during normal device operation, while holding I/O pins to a state defined by the data in the boundary-scan register.
USER0	00 0000 1100	This instruction allows you to define the scan chain between TDI and TDO in the MAX II logic array. This instruction is also used for custom logic and JTAG interfaces.
USER1	00 0000 1110	This instruction allows you to define the scan chain between TDI and TDO in the MAX II logic array. This instruction is also used for custom logic and JTAG interfaces.
IEEE 1532 instructions	(2)	IEEE 1532 ISC instructions used when programming a MAX II device via the JTAG port.

Notes to Table 3–1:

- (1) HIGHZ, CLAMP, and EXTEST instructions do not disable weak pull-up resistors or bus hold features.
- (2) These instructions are shown in the 1532 BSDL files, which will be posted on the Altera® website at www.altera.com when they are available.



Unsupported JTAG instructions should not be issued to the MAX II device as this may put the device into an unknown state, requiring a power cycle to recover device operation.

The MAX II device instruction register length is 10 bits and the USERCODE register length is 32 bits. Table 3–2 and Table 3–3 show the boundary-scan register length and device IDCODE information for MAX II devices.

Table 3–2. MAX II Boundary-Scan Register Length

Device	Boundary-Scan Register Length
EPM240	240
EPM570	480
EPM1270	636
EPM2210	816

Table 3–3. 32-Bit MAX II Device IDCODE (Part 1 of 2)

Device	Binary IDCODE (32 Bits) (1)				HEX IDCODE
	Version (4 Bits)	Part Number	Manufacturer Identity (11 Bits)	LSB (1 Bit) (2)	
EPM240 EPM240G	0000	0010 0000 1010 0001	000 0110 1110	1	0x020A10DD
EPM570 EPM570G	0000	0010 0000 1010 0010	000 0110 1110	1	0x020A20DD
EPM1270 EPM1270G	0000	0010 0000 1010 0011	000 0110 1110	1	0x020A30DD
EPM2210 EPM2210G	0000	0010 0000 1010 0100	000 0110 1110	1	0x020A40DD

I/O Pins Remain Tri-Stated during Power-Up

A device that does not support hot-socketing may interrupt system operation or cause contention by driving out before or during power-up. In a hot socketing situation, the MAX II device's output buffers are turned off during system power-up. MAX II devices do not drive out until the device attains proper operating conditions and is fully configured. Refer to [“Power-On Reset Circuitry” on page 4-5](#) for information about turn-on voltages.

Signal Pins Do Not Drive the V_{CCIO} or V_{CCINT} Power Supplies

MAX II devices do not have a current path from I/O pins or $GCLK[3..0]$ pins to the V_{CCIO} or V_{CCINT} pins before or during power-up. A MAX II device may be inserted into (or removed from) a system board that was powered up without damaging or interfering with system-board operation. When hot socketing, MAX II devices may have a minimal effect on the signal integrity of the backplane.

AC and DC Specifications

You can power up or power down the V_{CCIO} and V_{CCINT} pins in any sequence. During hot socketing, the I/O pin capacitance is less than 8 pF. MAX II devices meet the following hot socketing specifications:

- The hot socketing DC specification is: $|I_{IOPIN}| < 300 \mu A$.
- The hot socketing AC specification is: $|I_{IOPIN}| < 8 \text{ mA}$ for 10 ns or less.



MAX II devices are immune to latch-up when hot socketing. If the TCK JTAG input pin is driven high during hot socketing, the current on that pin might exceed the specifications above.

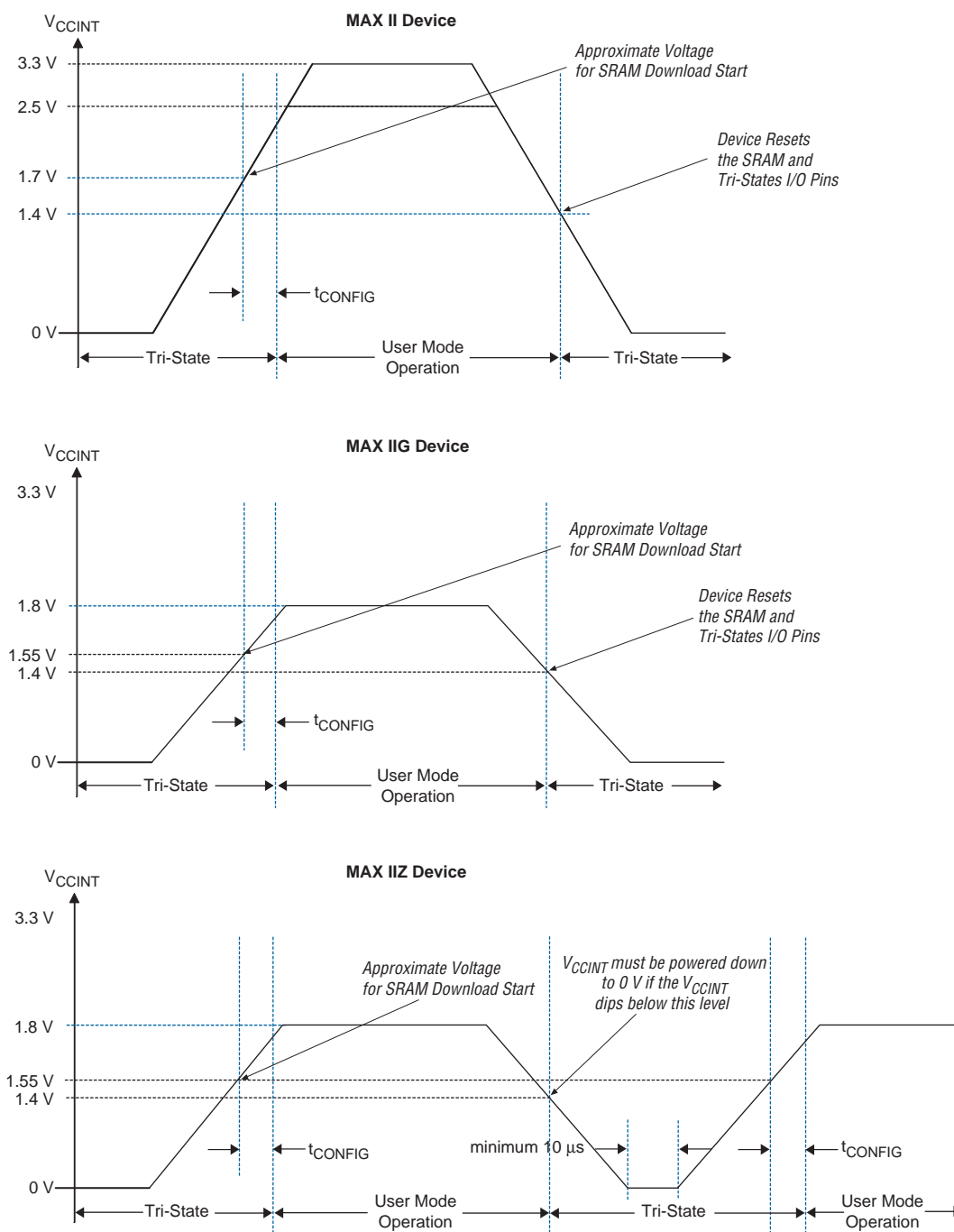
I_{IOPIN} is the current at any user I/O pin on the device. The AC specification applies when the device is being powered up or powered down. This specification takes into account the pin capacitance but not board trace and external loading capacitance. Additional capacitance for trace, connector, and loading must be taken into consideration separately. The peak current duration due to power-up transients is 10 ns or less.

The DC specification applies when all V_{CC} supplies to the device are stable in the powered-up or powered-down conditions.

Hot Socketing Feature Implementation in MAX II Devices

The hot socketing feature turns off (tri-states) the output buffer during the power-up event (either V_{CCINT} or V_{CCIO} supplies) or power-down event. The hot-socket circuit generates an internal HOTSKT signal when either V_{CCINT} or V_{CCIO} is below the threshold voltage during power-up or power-down. The HOTSKT signal cuts off the output buffer to make sure that no DC current (except for weak pull-up leaking) leaks through the pin. When V_{CC} ramps up very slowly during power-up, V_{CC} may still be relatively low even after the power-on reset (POR) signal is released and device configuration is complete.

Figure 4-5. Power-Up Characteristics for MAX II, MAX IIG, and MAX IIZ Devices (Note 1), (2)



Notes to Figure 4-5:

- (1) Time scale is relative.
- (2) Figure 4-5 assumes all V_{CCIO} banks power up simultaneously with the V_{CCINT} profile shown. If not, t_{CONFIG} stretches out until all V_{CCIO} banks are powered.



After SRAM configuration, all registers in the device are cleared and released into user function before I/O tri-states are released. To release clears after tri-states are released, use the `DEV_CLRn` pin option. To hold the tri-states beyond the power-up configuration time, use the `DEV_OE` pin option.

Power-Up Timing

Table 5–12 shows the power-up timing characteristics for MAX II devices.

Table 5–12. MAX II Power-Up Timing

Symbol	Parameter	Device	Min	Typ	Max	Unit
t_{CONFIG} (1)	The amount of time from when minimum V_{CCINT} is reached until the device enters user mode (2)	EPM240	—	—	200	μs
		EPM570	—	—	300	μs
		EPM1270	—	—	300	μs
		EPM2210	—	—	450	μs

Notes to Table 5–12:

- (1) Table 5–12 values apply to commercial and industrial range devices. For extended temperature range devices, the t_{CONFIG} maximum values are as follows:
- | | |
|---------|-------------------|
| Device | Maximum |
| EPM240 | 300 μs |
| EPM570 | 400 μs |
| EPM1270 | 400 μs |
| EPM2210 | 500 μs |
- (2) For more information about POR trigger voltage, refer to the *Hot Socketing and Power-On Reset in MAX II Devices* chapter in the *MAX II Device Handbook*.

Power Consumption

Designers can use the Altera® PowerPlay Early Power Estimator and PowerPlay Power Analyzer to estimate the device power.



For more information about these power analysis tools, refer to the *Understanding and Evaluating Power in MAX II Devices* chapter in the *MAX II Device Handbook* and the *PowerPlay Power Analysis* chapter in volume 3 of the *Quartus II Handbook*.

Timing Model and Specifications

MAX II devices timing can be analyzed with the Altera Quartus® II software, a variety of popular industry-standard EDA simulators and timing analyzers, or with the timing model shown in Figure 5–2.

MAX II devices have predictable internal delays that enable the designer to determine the worst-case timing of any design. The software provides timing simulation, point-to-point delay prediction, and detailed timing analysis for device-wide performance evaluation.

Table 5-13. MAX II Device Timing Model Status (Part 2 of 2)

Device	Preliminary	Final
EPM1270	—	✓
EPM2210	—	✓

Note to Table 5-13:

- (1) The MAX IIZ device timing models are only available in the Quartus II software version 8.0 and later.

Performance

Table 5-14 shows the MAX II device performance for some common designs. All performance values were obtained with the Quartus II software compilation of megafunctions. Performance values for -3, -4, and -5 speed grades are based on an EPM1270 device target, while -6, -7, and -8 speed grades are based on an EPM570Z device target.

Table 5-14. MAX II Device Performance

Resource Used	Design Size and Function	Resources Used			Performance						Unit
					MAX II / MAX IIG			MAX IIZ			
		Mode	LEs	UFM Blocks	−3 Speed Grade	−4 Speed Grade	−5 Speed Grade	−6 Speed Grade	−7 Speed Grade	−8 Speed Grade	
LE	16-bit counter (1)	—	16	0	304.0	247.5	201.1	184.1	123.5	118.3	MHz
	64-bit counter (1)	—	64	0	201.5	154.8	125.8	83.2	83.2	80.5	MHz
	16-to-1 multiplexer	—	11	0	6.0	8.0	9.3	17.4	17.3	20.4	ns
	32-to-1 multiplexer	—	24	0	7.1	9.0	11.4	12.5	22.8	25.3	ns
	16-bit XOR function	—	5	0	5.1	6.6	8.2	9.0	15.0	16.1	ns
	16-bit decoder with single address line	—	5	0	5.2	6.6	8.2	9.2	15.0	16.1	ns
UFM	512 × 16	None	3	1	10.0	10.0	10.0	10.0	10.0	10.0	MHz
	512 × 16	SPI (2)	37	1	8.0	8.0	8.0	9.7	9.7	9.7	MHz
	512 × 8	Parallel (3)	73	1	(4)	(4)	(4)	(4)	(4)	(4)	MHz
	512 × 16	I²C (3)	142	1	100 (5)	100 (5)	100 (5)	100 (5)	100 (5)	100 (5)	kHz

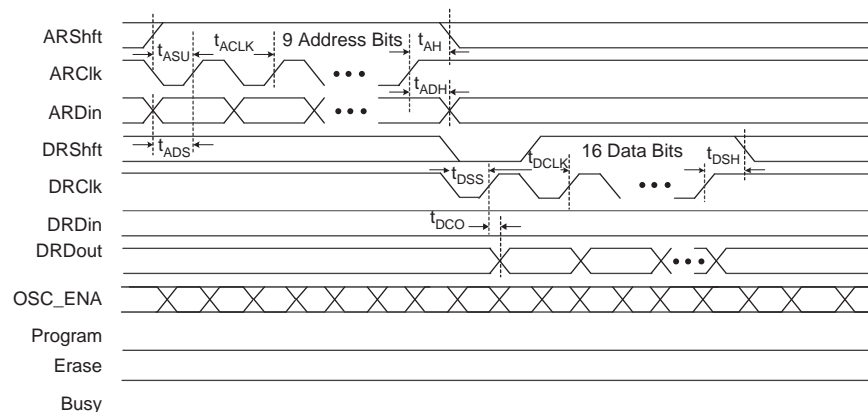
Notes to Table 5-14:

- (1) This design is a binary loadable up counter.
- (2) This design is configured for read-only operation in Extended mode. Read and write ability increases the number of LEs used.
- (3) This design is configured for read-only operation. Read and write ability increases the number of LEs used.
- (4) This design is asynchronous.
- (5) The I²C megafunction is verified in hardware up to 100-kHz serial clock line (SCL) rate.

Table 5-21. UFM Block Internal Timing Microparameters (Part 3 of 3)

Symbol	Parameter	MAX II / MAX IIG						MAX IIZ						Unit
		-3 Speed Grade		-4 Speed Grade		-5 Speed Grade		-6 Speed Grade		-7 Speed Grade		-8 Speed Grade		
		Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	
t _{OE}	Delay from data register clock to data register output	180	—	180	—	180	—	180	—	180	—	180	—	ns
t _{RA}	Maximum read access time	—	65	—	65	—	65	—	65	—	65	—	65	ns
t _{OSCS}	Maximum delay between the OSC_ENA rising edge to the erase/program signal rising edge	250	—	250	—	250	—	250	—	250	—	250	—	ns
t _{OSCH}	Minimum delay allowed from the erase/program signal going low to OSC_ENA signal going low	250	—	250	—	250	—	250	—	250	—	250	—	ns

Figure 5-3 through Figure 5-5 show the read, program, and erase waveforms for UFM block timing parameters shown in Table 5-21.

Figure 5-3. UFM Read Waveforms

External Timing Parameters

External timing parameters are specified by device density and speed grade. All external I/O timing parameters shown are for the 3.3-V LVTTTL I/O standard with the maximum drive strength and fast slew rate. For external I/O timing using standards other than LVTTTL or for different drive strengths, use the I/O standard input and output delay adders in [Table 5-27](#) through [Table 5-31](#).



For more information about each external timing parameters symbol, refer to the [Understanding Timing in MAX II Devices](#) chapter in the *MAX II Device Handbook*.

[Table 5-23](#) shows the external I/O timing parameters for EPM240 devices.

Table 5-23. EPM240 Global Clock External I/O Timing Parameters (Part 1 of 2)

Symbol	Parameter	Condition	MAX II / MAX IIG						MAX IIZ						Unit
			-3 Speed Grade		-4 Speed Grade		-5 Speed Grade		-6 Speed Grade		-7 Speed Grade		-8 Speed Grade		
			Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	
t _{PD1}	Worst case pin-to-pin delay through 1 look-up table (LUT)	10 pF	—	4.7	—	6.1	—	7.5	—	7.9	—	12.0	—	14.0	ns
t _{PD2}	Best case pin-to-pin delay through 1 LUT	10 pF	—	3.7	—	4.8	—	5.9	—	5.8	—	7.8	—	8.5	ns
t _{SU}	Global clock setup time	—	1.7	—	2.2	—	2.7	—	2.4	—	4.1	—	4.6	—	ns
t _H	Global clock hold time	—	0	—	0	—	0	—	0	—	0	—	0	—	ns
t _{CO}	Global clock to output delay	10 pF	2.0	4.3	2.0	5.6	2.0	6.9	2.0	6.6	2.0	8.1	2.0	8.6	ns
t _{CH}	Global clock high time	—	166	—	216	—	266	—	253	—	335	—	339	—	ps
t _{CL}	Global clock low time	—	166	—	216	—	266	—	253	—	335	—	339	—	ps
t _{CNT}	Minimum global clock period for 16-bit counter	—	3.3	—	4.0	—	5.0	—	5.4	—	8.1	—	8.4	—	ns